

AN 1988:42446 HCPLUS
 DN 108:42446
 TI Copper alloys for leads in semiconductor devices
 IN Futatsuka, Rensei; Kumagai, Seiji; Izumida, Masuhiro
 PA Tamagawa Metal and Machinery Co., Ltd., Japan
 SO Jpn. Kokai Tokkyo Koho, 4 pp.
 CODEN: JKXXAF
 DT Patent
 LA Japanese
 FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 62093325	A2	19870428	JP 1985-232559	19851018
	JP 64000449	B4	19890106		

AB The Cu alloys contain Fe 2-2.4, P 0.001-0.1, Zn 0.01-1, and Mg 0.001-0.1%. The Mg addn. improves heat resistance and strength without lowering elongation and elec. cond. The Cu alloys show good solderability. Thus, molten Cu alloy (contg. Fe 2.02, P 0.00188, Zn 0.012, and Mg 0.002%) was semicontinuously cast into an ingot slab 150 mm thick, and hot-rolled into a plate 11 mm thick. The trimmed plate was alternately cold rolled and annealed to manuf. a strip 0.25 mm thick, and then annealed for strain relief at 250-350.degree.. The strip showed tensile strength 52.1 kg/mm², elongation 5%, elec. cond. 64% of IACS, and softening point 410.degree.. A solder coating showed good adhesion when the strip was bent after heating in air at 150.degree. for 500 h.

1, 2, 8,